

REMARKS

Claims 21-23, 28 and 31-34 are pending. Claims 1-17 have been withdrawn. Claims 18-20, 24-27 and 29-30 have been canceled. New claim 34 has been added to clarify the subject matter of claim 19. Claim 19, as well as dependent claims 20 and 29-30, have been subsequently canceled. No new matter has been added.

Allowable subject matter

The Examiner has indicated that claims 21-23, 28 and 31-33 recite allowable subject matter.

Applicants thank the Examiner for the allowable subject matter.

Claim Rejections 35 USC 102 and 103

Claims 19 and 29 have been rejected under 35 USC 102 as being anticipated by ANAND (2001/0013657). Claims 20 and 30 have been rejected under 35 USC 103(a) as being unpatentable over ANAND.

Claims 19-20 and 29-30 have been canceled. Accordingly, the rejection of claims 19-20 and 29-30 are moot. Applicants respectfully request withdrawal of this rejection.

New Claims

Claim 34 has been added to clarify the subject matter of claim 19. Claim 19, as well as dependent claims 20 and 29-30, have been canceled. Claim 34 should be allowable over the prior art for at least the following reasons.

New claim 34 recites:

34. (New) A semiconductor device comprising:
- a lower layer wiring;
 - an interlayer insulating film covering the lower layer wiring;
 - a via hole formed in the interlayer insulating film; and
 - an upper layer wiring having a pad portion, disposed over the interlayer insulating film and connected to the lower layer wiring through the via hole,

wherein no hole connecting the upper layer wiring and the lower layer wiring is formed under the pad portion. (Emphasis Added)

Applicants respectfully submit that the above bolded features of claim 34 are not taught or suggested by the ANAND reference for at least the following reasons.

For example, FIG. 45 of the ANAND reference shows a structure having a bonding wire 28 connected to a bonding pad 21. This structure is adjacent a metal portion 20b. However, insulating layer 29 exists between metal portion 20b and the structure (i.e., wire 28 and pad 21) preventing the structure from being connected to metal portion 20b. In other words, the structure **is not connected** to the metal portion. In contrast, claim 34 of the present invention recites "a pad portion ... **connected** to the lower layer wiring through the via hole." Thus, claim 34 is not anticipated by the ANAND reference for at least this reason.

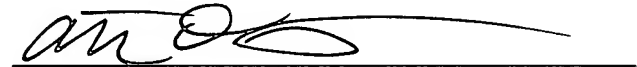
Conclusion

Applicants respectfully requests allowance of all claims.

Please apply any other charges or credits to deposit account 06-1050.

Respectfully submitted,

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